



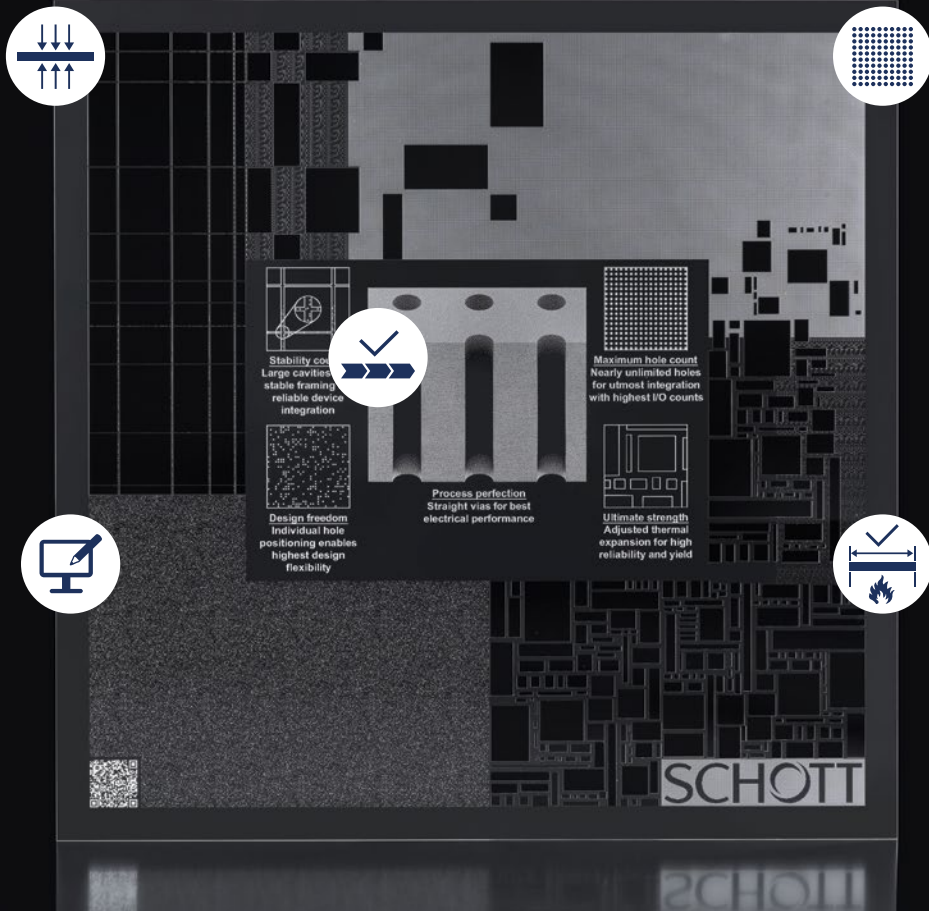
# FLEXINITY<sup>®</sup> connect

SCHOTT's innovative structuring portfolio expansion for the advanced packaging industry

With FLEXINITY<sup>®</sup> connect, SCHOTT is expanding its FLEXINITY<sup>®</sup> portfolio towards smaller holes in high numbers being extremely close to each other. Various glass types and formats in a wide range of thicknesses are available at the sampling level, allowing SCHOTT to support customer projects at different stages of development. Providing tailored solutions for a wide range of applications.

Properties*	Specification
Glass types	BOROFLOAT <sup>®</sup> 33, D 263 <sup>®</sup> T eco
Glass thicknesses	0.2 – 1.0 mm
TGV diameter (round only)	50 – 200 µm
TGV Roundness	≥ 0.9
Diameter tolerance	± 10 µm
Aspect ratio (max. thickness 1.0 mm)	≤ 1:20
Taper shape	Straight only
Taper angle	≤ 3°
Pitch	≥ 90 µm
Bridge distance between TGV's	≥ 40 µm
Position tolerance pattern	± 10 µm
Typical format	Wafer (12 inch)   Panels (515 x 510 mm)

\*Tighter specification upon request

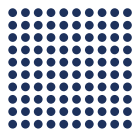


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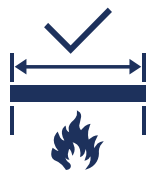
Triggered by the advanced packaging industry SCHOTT continuously develops its structuring portfolio towards even more extreme structuring elements such as an ultra small TGV radius down to 25 µm and ultra wide panel formats.



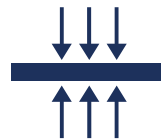
**Design freedom**  
Individual hole positioning enables highest design flexibility.



**Millions of holes\***  
Nearly unlimited holes for utmost integration with highest I/O counts.



**Improved reliability**  
Adjusted thermal expansion for high reliability and yield.



**Increased stability**  
Large cavities with stable framing for reliable device integration.



**Process readiness**  
Straight vias for best electrical performance.

\* Depending on design

